[Proposals to address issues]

## Respond to High Quality Requirements

Panasonic Connect Corporation
Circuit Formation Process Business Division





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## Agenda

Demand for high quality
Panasonic Solutions (Solution List)
High quality < System Software >
APC-5M (real-time unit monitoring)
APC System (APC-FB)
APC System (APC-FF/APC-MFB2)
Material Matching System (PanaCIM)
High Quality < Printer >
Top/Side Clamper
Mask Tension Feedback
Hybrid Adsorption
Toe Bend High Fill Squeegee
High Quality < Mounter >
LCR Checker
Load Checker V2, Mounted Load Trace
Recognition before adsorption: "polarity," "character"
Shield mounting inspection
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## **Demand for high quality**

Demand for electronic component mounting is becoming more diverse and sophisticated, including in the automotive industry, where EVs are becoming increasingly popular, and in the server industry, where performance improvements are required due to the advancement of AI. At the same time, there is an unchanging demand in all industries to ensure high quality.

Panasonic offers a variety of solutions that achieve high quality by combining various functions of mounter and printer and software.



## **Solutions by Panasonic**

High Quality < System Software >

Reduce losses caused by excessive maintenance and maintenance delays

APC-5M (Real-time unit monitoring) Stabilize solder position and volume to ensure printing quality

APC System (APC-FB)

Suppress effects of solder misalignment and mounting misalignment to ensure mounting quality

APC System (APC-FF/APC-MFB2)

Reduce defects caused by incorrect mounting materials

Material Matching System (PanaCIM)

High Quality < Printer >

Print properly even when there is PCB warpage

**Top/Side Clamper** 

Suppress defects caused by mask tension

**Mask Tension Feedback** 

Stabilize printing on highaspect openings

**Hybrid Adsorption** 

Stabilize printing on microopenings

Pre-bend High Filling Squeegee

High Quality < Mounter >

Suppress quality failure due to mis-setting of parts when switching models

**LCR Checker** 

Maintain lowload/constant-load mounting quality, and record and visualize

Load Checker V2 Mounting Load Trace Avoid poor mounting quality

Preadsorption
Recognition:
"Polarity" "Character"

Reduce mounting defects and repair time for shield case

Shield Mounting Inspection

## Reduce losses caused by excessive maintenance and maintenance delays

## **APC-5M** (Real-time unit monitoring)

Real-time monitoring of the status of units to be maintained on mounting machines (printers and mounting machines) for each unit. By changing the value, deterioration of the status is detected for each unit, and proper maintenance is promoted.

### **Detection of unit status**



Color	Status	Description	
	Not measured	Initial status	
	Normal	Normal Within the specification range	
	Semi-normal	Normal Within the specification range	
	Warning	Warning threshold has been reached	
	Abnormal	Normal Out of specification	

	Target Unit	Monitored item		
	PCB clamper	Clamper plane		
		Operating unit operating state		
		Dirt		
Printing machine	Vacuum pump	Vacuum rise time		
		Vacuum pump running time		
	Machine running time	Running distance		
	PCB transport section	PCB transport time		
	Mask recognition camera	Presence of foreign matter on camera		
	Solvent discharging section	Amount of solvent discharging		
	Blower	Operating time		
Mounting machine	Head	Clog		
		Holder sliding		
	Nozzle	Clog		
		Tip state		
Mo	Feeder	Feeder accuracy		

### Merit

Preventive maintenance before deterioration of the status is possible, and error stopping due to insufficient maintenance is suppressed

By analyzing the status of each unit, it is possible to visualize whether maintenance is necessary or unnecessary, and excessive maintenance is suppressed

## Stabilize solder position and volume to ensure printing quality

## **APC System (APC-FB)**

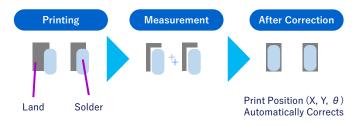
APC System automatically stabilizes print quality by statistically processing the solder measurement results from the Solder Pasete Inspection (SPI) machine and feeding them back to the printer to control the solder position and volume.

### **APC-FB** (Position)

Maintain print quality by feedback control of the solder print position



Print Position Correction Based on SPI Print Deviation Information



### **APC-FB** (Volume)

Automatically correct volume by using 3D solder inspection equipment and angle variable squeegee

Attack angle variable squeegee (optional)



Automatically adjusts the squeegee angle according to the volume measurement result



### Merit

Stable print quality is achieved by automatically correcting the print position based on the print misalignment information from the SPI

High quality printing is maintained by quickly correcting the print position misalignment caused by material factors such as model switching or the board

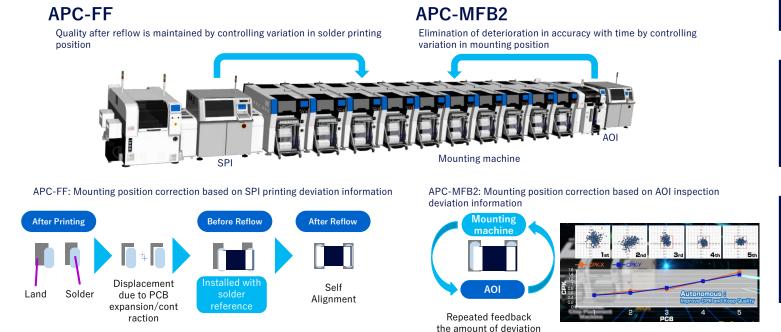
Optimum solder volume is maintained by automatically adjusting the filling force by changing the squeegee attack angle based on the volume information from the SPI

High Quality < System Software >

# Suppress effects of solder misalignment and mounting misalignment to ensure mounting quality

## **APC System (APC-FF/APC-MFB2)**

Maintaining mounting quality by controlling solder printing and component mounting variation in cooperation with other companies' inspection facilities.



### Merit

#### APC-FF

Components are installed at the optimum position based on the SPI solder measurement position, and high quality mounting is achieved by effectively utilizing the self-alignment effect

#### APC-MFB2

Components are installed by correcting misalignment based on AOI measurement results, and stable mounting quality is achieved by automatically correcting equipment fluctuation

By using APC-FF and MFB2 together (APC-MFB correction is applied based on the component mounting coordinates corrected by APC-FF), further high-quality mounting is realized.

## Reduce defects caused by incorrect mounting materials

## **Material Matching System (PanaCIM)**

If the wrong material is installed in accordance with the production data downloaded to the equipment, the interlock function of the equipment is activated, and production cannot continue automatically.

Scan the barcode of the material at the time of model switching, material replacement, or replenishment



\*Wireless scanner and related accessories must be provided by the customer.

### Merit

Match the barcode information of the material to be replaced with the production data to prevent incorrect setting of the material at the time of model switching, material replacement, or replenishment

Stop the facility (interlock) in case of incorrect matching or non-matching to prevent continued production due to incorrect setting

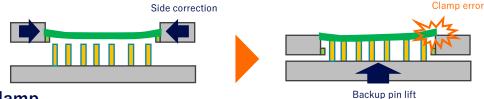
<sup>\*</sup>Please contact us for details on products compatible with each function.

## Print properly even when there is PCB warpage

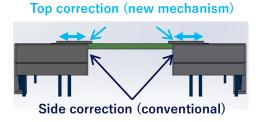
## **Top/Side Clamper**

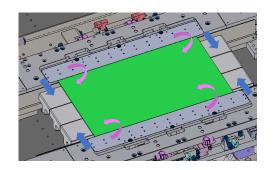
In addition to the conventional side clamper, a top clamper is adopted to hold the PCB from the top. This strengthens the solution to PCB warpage and further improves print quality.

### **Side Clamp**



Side + Top Clamp





### Merit

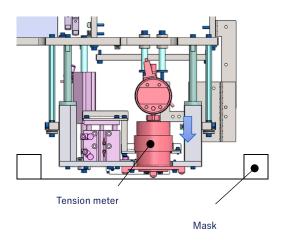
Corrects PCB warpage and improves printing quality by pressing from the top of the PCB.

Prevents the PCB from sticking to the mask after printing.

## Suppress defects caused by mask tension

### **Mask Tension Feedback**

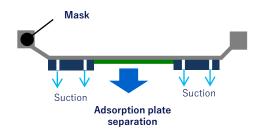
Check the mask condition by measuring the mask tension when setting the mask. Notify that the mask has changed to the optimum plate separation operation or that the mask has been replaced.



#### Tension is weak

- Mask suction plate separation
- Replacement announcement

#### **Mask Adsorption plate separation**



### Merit

Confirm the mask condition and realize stable printing

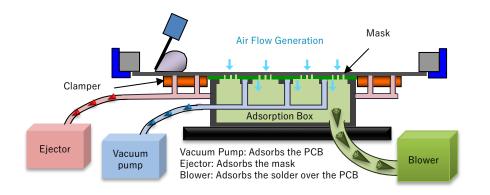
Realize the optimum plate separation operation

Notify the replacement of the mask

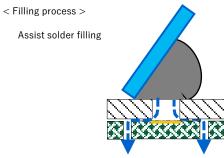
## Stabilize printing on high-aspect openings

## **Hybrid Adsorption**

To overcome the problems of solder filling in high-aspect openings of masks and solder disengagement during plate separation, stable printing can be continued by combining PCB adsorption by vacuum and mask suction by blower.

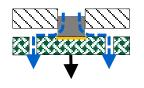


The blower generates air flow from the upper surface of the mask to the lower surface



< plate separation process >

Assist solder transfer



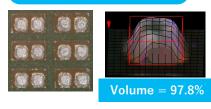
### Merit

Achieves stable printability due to high filling and good plate separation

Stable printing of small openings such as 0201 parts with high printing difficulty

Effective for stable printing of thin PCBs and PCBs with large warpage





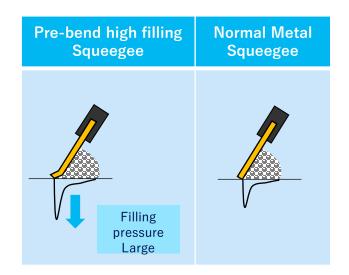
With Hybrid Adsorption

## Stabilize printing on micro-openings

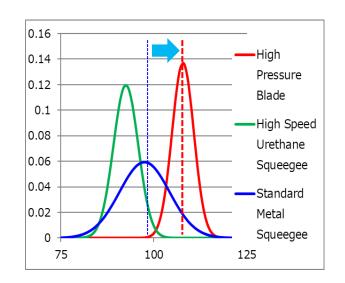
## **Pre-bend High Filling Squeegee**

For cream solder printing on small parts with a high aspect ratio of mask openings, a high bending-type filling squeegee is effective. It increases the filling pressure at the bent part of the tip, improving the volume fraction and suppressing dispersion.

### Filling pressure image



### Average volume: 10% improvement



### Merit

Easy to handle as usual metal squeegee

Achieves higher filling performance than urethane squeegee

Effective for industrial, automotive, and other PCBs with thick resist silk

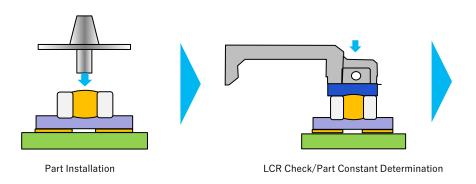
<sup>\*</sup>Please contact us for details on products compatible with each function.

## Suppress quality failure due to mis-setting of parts when switching models

### **LCR Checker**

LCR checker automatically checks the constant number of installed parts when starting production, supplying parts, or switching models. This function contributes to the production of good quality products by preventing incorrect mounting due to incorrect feeding, abnormal parts, or incorrect labeling on reels.

Judge whether the electrical characteristics of the parts are within the specified range before mounting



Target Part Size: 0402 to □6 mm
Target Parts: Resistance, Capacitor, Inductor, Diode

### Merit

Suppress quality defects caused by operators such as barcode affixing or incorrect setting of feeders, and quality defects caused by abnormal parts

Automatic recording of measurement data enhanced traceability

Reduction of first-time inspection and ICT manhours

## Maintain low-load/constant-load mounting quality, and record and visualize

### **Load Checker V2/Mounted Load Trace**

With the increase in the number of small parts, mounting load management becomes more important. By visualizing the nozzle sliding condition of the mounting head, performance maintenance and stable operation are realized. In addition, by recording the actual load at each mounting point, the quality is visualized and contributes to quality improvement.

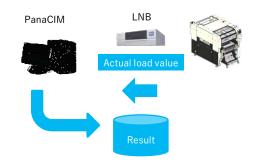
#### **Load Checker V2**



- Check and calibrate the load for each nozzle by load cell
- · Automatic recording of measurement data



#### **Mounted Load Trace Function**



Trace the actual load at each mounting point

Table	Feeder	Туре	Nozzle	Load
1	15	8 mm	225	0.81
2	20	8 mm	230	0.85

### Merit

#### **Load Checker**

Automatically checks the mounted load on a regular basis, contributing to quality improvement by maintaining signs.

#### Mounted Load Trace

Contribute to quality improvement by visualizing quality by recording load results at each mounting point

## **Avoid poor mounting quality**

## Recognition before suction: "polarity" "character"

Check tray and reel components before suction to prevent mis-setting.

#### Recognition of polarity before suction

#### **Detection of wrong part direction**

#### Inspection mode

Splicing detection, others







### Part inspection location

2 locations





### Part inspection method

Luminance Pattern match





4 locations

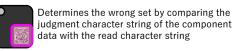
If NG, the image is displayed and single stop is performed. According to the inspection setting, the angle can be automatically corrected for suction and mounting.

### Recognition of character before suction

#### **Detection of wrong part, part trace**

Misset parts matching





#### **Trace Management**





Adds the read lot name and other information to the implementation log file and outputs it to the higher system.

### Merit

#### Recognition of polarity

When the polarity direction is wrong, the image is displayed and single stop is performed to prevent incorrect setting

#### Recognition of character

Recognizes the part number and detects the wrong part number to prevent incorrect production

#### Character recognition

Supports traceability by recognizing the manufacturing lot number of a component

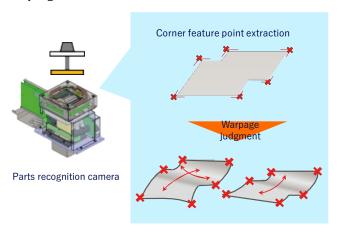
## Reduce mounting defects and repair time for shield case

## **Shield Mounting Inspection**

To reduce mounting defects and repair time for shield case by performing warpage inspection and misalignment inspection of shield case, which are not normally inspected by AOI, on the mounter.

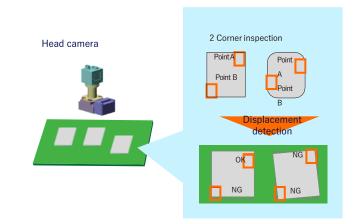
### Warpage inspection before installing shield case

Warpage inspection of shield case is performed by part recognition. If it is judged that the part is deformed, the part is discarded by recognition error judgment.



### Mounted position recognition

After mounting the shield parts, use the head camera of the mounting machine to easily inspect the warpage and dislocation of the shield parts. Error stop when dislocation is judged



### Merit

### Warpage inspection before installing

Reducing mounting defects due to defective shield cases by performing warpage inspection on the mounter

#### Mounted position recognition

Reducing mounting defects and repair time after reflow by performing post-installation inspection on the mounter

## **Related Contents**

**Our Vision** 

**Other Solutions** 

**Case Study** 

Movies





Solutions - Factory Automation - Panasonic Connect



Case Study



Video Library - Library - Factory Automation - Panasonic Connect

## Related Products/Service

**Electronic Component Mounting-related Systems** 

**Mounting Software** 

**Operation & Maintenance** 

**Electronic Materials** 

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**Mounting Software** 

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Product website

